



	XS170	Units
Load Voltage	350	V
Load Current	100	mA
Max R _{ON}	50	Ω

Description

XS170 is a 350V, 100mA, 50Ω 1-Form-A relay with an optocoupler in a single package. It provides an economical solution for cost sensitive applications.

Features

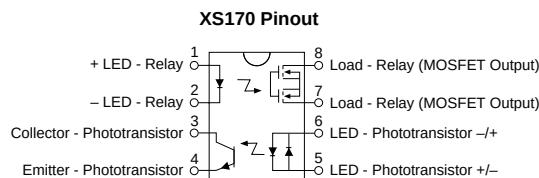
- Small 8 Pin DIP Package
- Low Drive Power Requirements (TTL/CMOS Compatible)
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- 3750V_{RMS} Input/Output Isolation
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available

Approvals

- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- BSI Certified to:
 - BS EN 60950:1992 (BS7002:1992)
 - Certificate #: 7344
 - BS EN 41003:1993
 - Certificate #: 7344

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hookswitch
 - Dial Pulsing
 - Ground Start
 - Ringer Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
 - Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Part #	Description
XS170	8 Pin DIP (50/Tube)
XS170S	8 Pin Surface Mount (50/Tube)
XS170STR	8 Pin Surface Mount (1000/Reel)



Parameter	Min	Typ	Max	Units
Input Power Dissipation	-	-	150 ¹	mW
Input Control Current	-	-	50	mA
Peak (10ms)	-	-	1	A
Reverse Input Voltage	-	-	5	V
Total Power Dissipation	-	-	800 ²	mW
Isolation Voltage Input to Output	3750	-	-	V _{RMS}
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature DIP Package	-	-	+260	°C
Flatpack/Surface Mount Package (10 Seconds Max.)	-	-	+220	°C

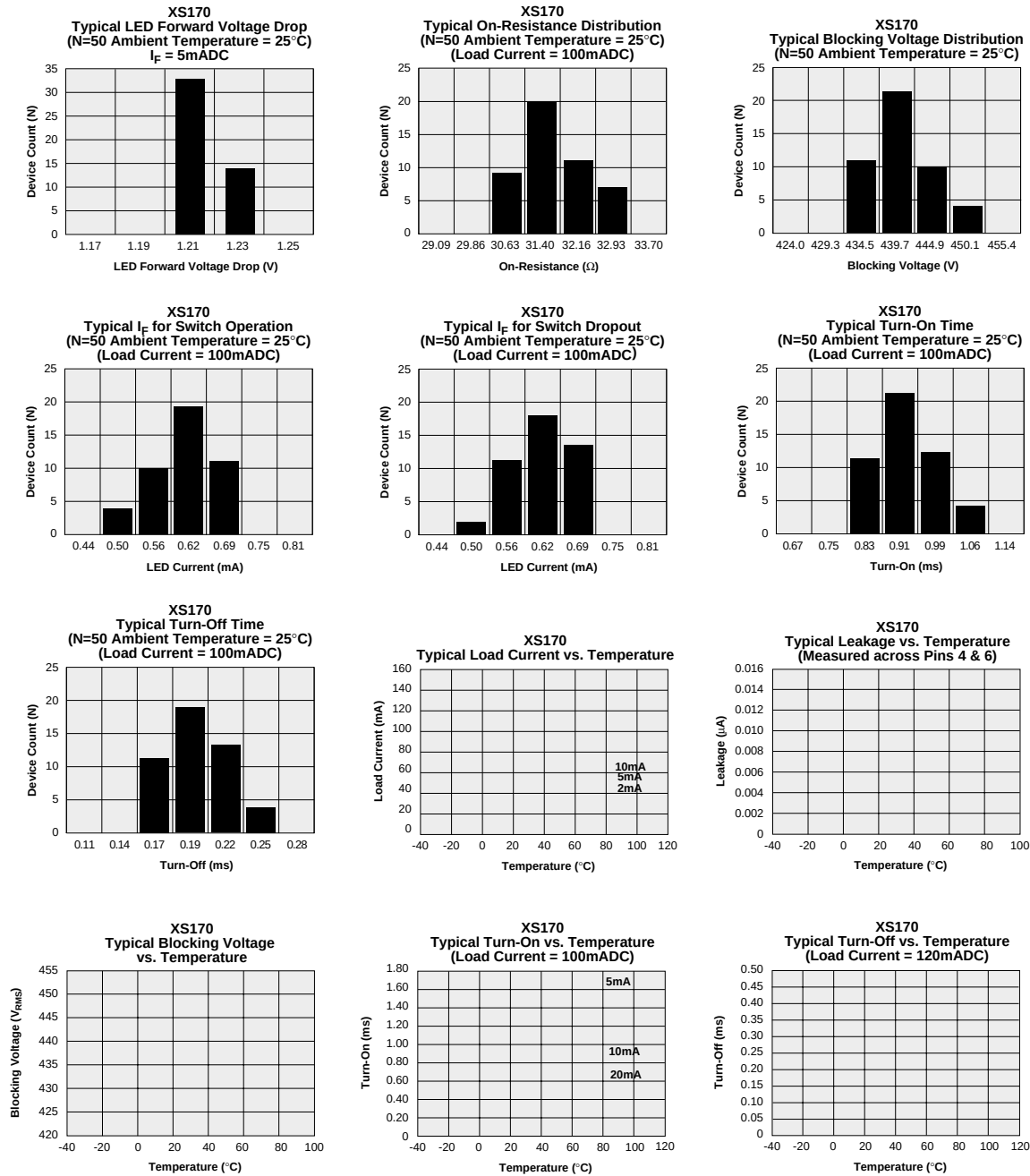
¹ Derate Linearly 1.33 mW/°C

² Derate Linearly 6.67 mW/°C

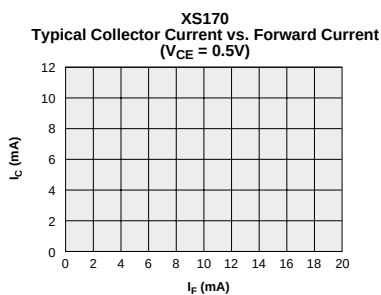
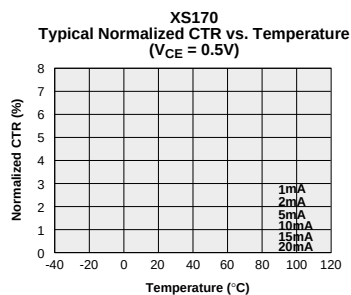
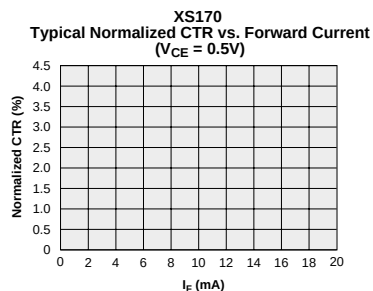
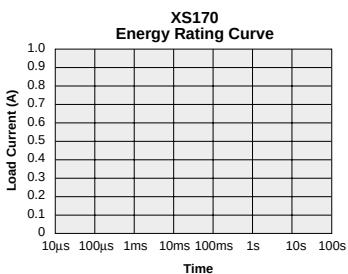
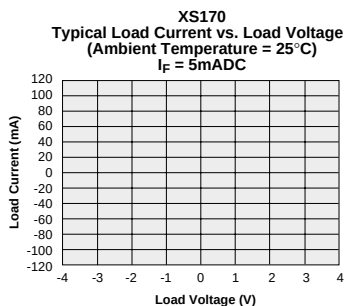
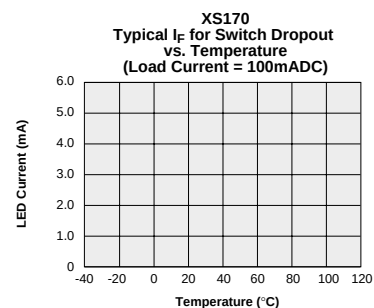
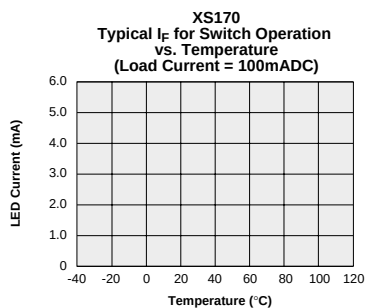
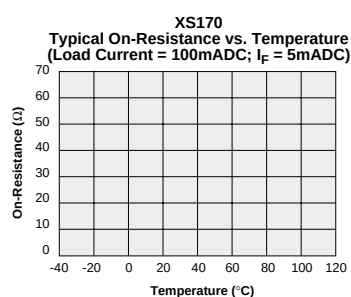
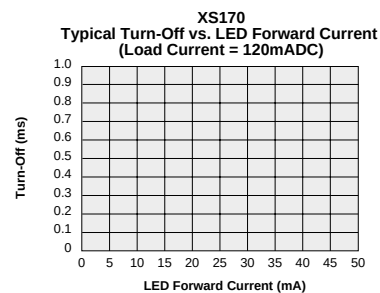
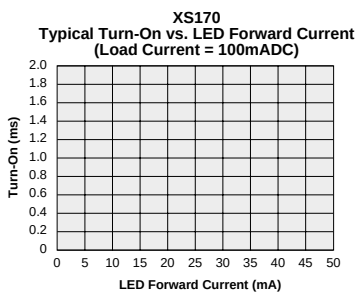
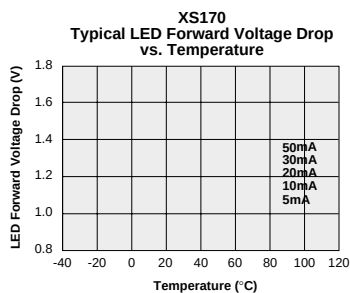
Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics @ 25°C						
Load Voltage (Peak)	-	V _L	-	-	350	V
Load Current (Continuous)	-	I _L	-	-	100	mA
Peak Load Current	10ms	I _{LPK}	-	-	350	mA
On-Resistance	I _L =120mA	R _{ON}	-	33	50	Ω
Off-State Leakage Current	V _L =350V	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	T _{ON}	-	-	5	ms
Turn-Off	I _F =5mA, V _L =10V	T _{OFF}	-	-	5	ms
Output Capacitance	50V; f=1MHz	C _{OUT}	-	25	-	pF
Load Current Limit		I _{OL}	-	-	-	mA
Input Characteristics @ 25°C						
Input Control Current	I _L =120mA	I _F	2	-	50	mA
Input Dropout Current	-	I _F	0.4	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics @ 25°C						
Phototransistor Blocking Voltage	$I_C=10\mu A$	BV_{CEO}	20	50	-	V
Phototransistor Output Current	$V_{CE}=5V, I_F=0mA$	I_{CEO}	-	50	500	nA
Saturation Voltage	$I_C=2mA, I_F=16mA$	V_{SAT}	-	0.3	0.5	V
Current Transfer Ratio	$I_F=6mA, V_{CE}=0.5V$	CTR	33	100	-	%
Input Characteristics @ 25°C						
Input Control Current	$I_C=2mA, V_{CE}=0.5V$	I_F	6	2	100	mA
Input Voltage Drop	$I_F=5mA$	V_F	0.9	1.2	1.4	V
Input Current (Detector must be off)	$I_C=1\mu A, V_{CE}=5V$	I_F	5	25	-	μA
Input to Output Capacitance (Relay Only)	-	$C_{I/O}$	-	3	-	pF
Capacitance Input to Output	-	-	-	3	-	pF
Input to Output Isolation	-	$V_{I/O}$	3750	-	-	V_{RMS}

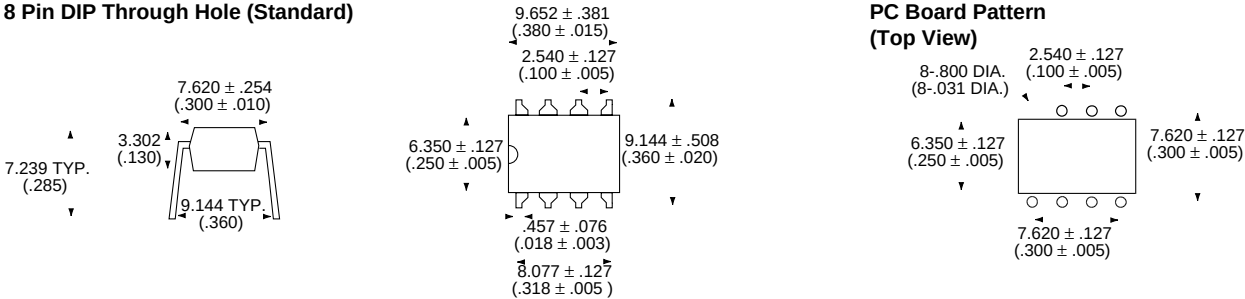


The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

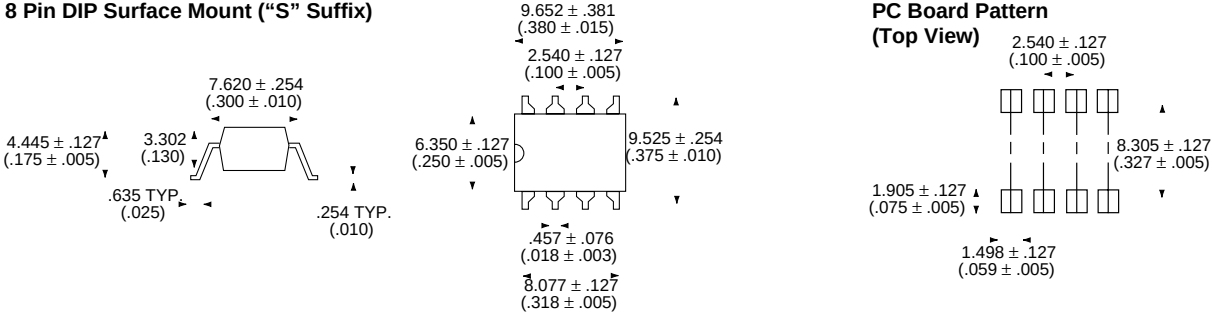


*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

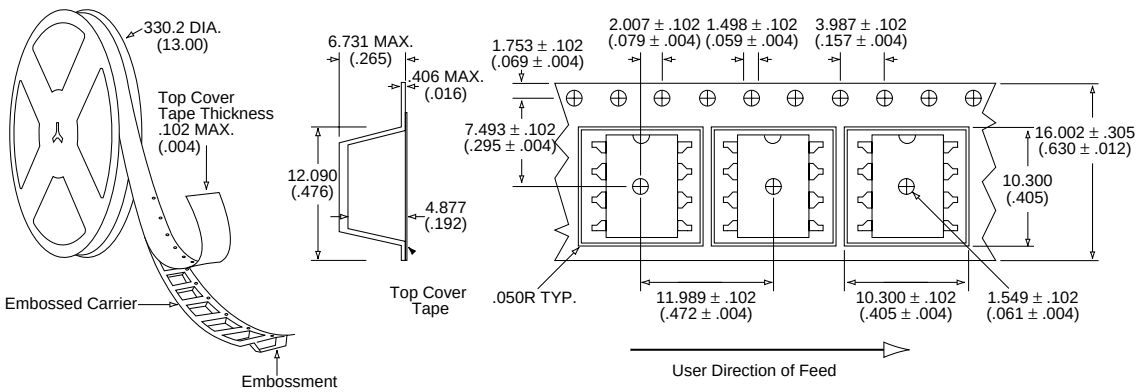
8 Pin DIP Through Hole (Standard)



8 Pin DIP Surface Mount ("S" Suffix)



Tape and Reel Packaging for 8 Pin Surface Mount Package



Dimensions
mm
(inches)



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